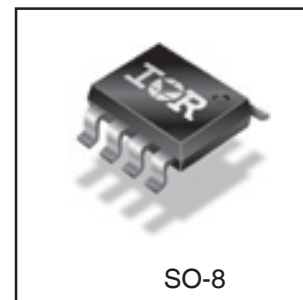
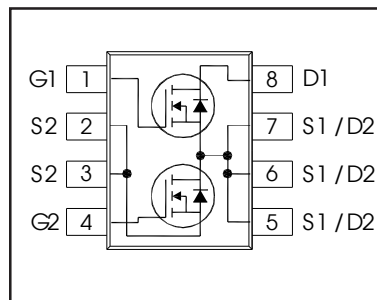


HEXFET® Power MOSFET

V_{DS}	30	V
$R_{DS(on) \text{ max Q1}}$ (@ $V_{GS} = 10V$)	16.2	m Ω
$R_{DS(on) \text{ max Q2}}$ (@ $V_{GS} = 10V$)	10.8	
Q_g (typical) Q1	7.5	nC
Q_g (typical) Q2	14	
I_D (@ $T_A = 25^\circ C$) Q1	7.6	A
I_D (@ $T_A = 25^\circ C$) Q2	11	



Applications

- Dual SO-8 MOSFET for POL Converters in Notebook Computers, Servers, Graphics Cards, Game Consoles and Set-Top Box

Features

Industry-standard pinout SO-8 Package
Compatible with Existing Surface Mount Techniques
RoHS Compliant, Halogen-Free
MSL1, Industrial qualification

Benefits

Multi-Vendor Compatibility
Easier Manufacturing
Environmentally Friendlier
Increased Reliability

Base Part Number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
IRF7904PbF-1	SO-8	Tube/Bulk	95	IRF7904PbF-1
		Tape and Reel	4000	IRF7904TRPbF-1

Absolute Maximum Ratings

	Parameter	Q1 Max.	Q2 Max.	Units
V _{DS}	Drain-to-Source Voltage	30		V
V _{GS}	Gate-to-Source Voltage	± 20		
I _D @ T _A = 25°C	Continuous Drain Current, V _{GS} @ 10V	7.6	11	A
I _D @ T _A = 70°C	Continuous Drain Current, V _{GS} @ 10V	6.1	8.9	
I _{DM}	Pulsed Drain Current ①	61	89	
P _D @T _A = 25°C	Power Dissipation	1.4	2.0	W
P _D @T _A = 70°C	Power Dissipation	0.9	1.3	
	Linear Derating Factor	0.011	0.016	W/°C
T _J	Operating Junction and	-55 to + 150		°C
T _{STG}	Storage Temperature Range			

Thermal Resistance

	Parameter	Q1 Max.	Q2 Max.	Units
$R_{\theta JL}$	Junction-to-Drain Lead ⑤	20	20	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient ④ ⑤	90	62.5	

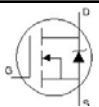
Static @ T_J = 25°C (unless otherwise specified)

	Parameter		Min.	Typ.	Max.	Units	Conditions
BV _{DSS}	Drain-to-Source Breakdown Voltage	Q1&Q2	30	—	—	V	V _{GS} = 0V, I _D = 250μA
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	Q1	—	0.024	—	V/°C	Reference to 25°C, I _D = 1mA
		Q2	—	0.024	—		
R _{DS(on)}	Static Drain-to-Source On-Resistance	Q1	—	11.4	16.2	mΩ	V _{GS} = 10V, I _D = 7.6A ③
			—	14.5	20.5		V _{GS} = 4.5V, I _D = 6.1A ③
		Q2	—	8.6	10.8		V _{GS} = 10V, I _D = 11A ③
			—	10	13		V _{GS} = 4.5V, I _D = 8.8A ③
V _{GS(th)}	Gate Threshold Voltage	Q1&Q2	1.35	—	2.25	V	Q1: V _{DS} = V _{GS} , I _D = 25μA
ΔV _{GS(th)} /ΔT _J	Gate Threshold Voltage Coefficient	Q1	—	-5.0	—	mV/°C	Q2: V _{DS} = V _{GS} , I _D = 50μA
		Q2	—	-5.0	—		
I _{DSS}	Drain-to-Source Leakage Current	Q1&Q2	—	—	1.0	μA	V _{DS} = 24V, V _{GS} = 0V
		Q1&Q2	—	—	150		V _{DS} = 24V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Forward Leakage	Q1&Q2	—	—	100	nA	V _{GS} = 20V
	Gate-to-Source Reverse Leakage	Q1&Q2	—	—	-100		V _{GS} = -20V
g _{fs}	Forward Transconductance	Q1	17	—	—	S	V _{DS} = 15V, I _D = 6.1A
		Q2	23	—	—		V _{DS} = 15V, I _D = 8.8A
Q _g	Total Gate Charge	Q1	—	7.5	11	nC	Q1 V _{DS} = 15V V _{GS} = 4.5V, I _D = 6.1A Q2 V _{DS} = 15V V _{GS} = 4.5V, I _D = 8.8A
		Q2	—	14	21		
Q _{gs1}	Pre-V _{th} Gate-to-Source Charge	Q1	—	2.2	—		
		Q2	—	3.7	—		
Q _{gs2}	Post-V _{th} Gate-to-Source Charge	Q1	—	0.6	—		
		Q2	—	1.1	—		
Q _{gd}	Gate-to-Drain Charge	Q1	—	2.5	—		
		Q2	—	4.8	—		
Q _{godr}	Gate Charge Overdrive	Q1	—	2.2	—		
		Q2	—	4.4	—		
Q _{sw}	Switch Charge (Q _{gs2} + Q _{gd})	Q1	—	3.1	—	nC	V _{DS} = 16V, V _{GS} = 0V
		Q2	—	5.9	—		
Q _{oss}	Output Charge	Q1	—	4.5	—	nC	
		Q2	—	9.1	—		
R _G	Gate Resistance	Q1	—	3.2	4.8	Ω	
		Q2	—	2.9	4.4		
t _{d(on)}	Turn-On Delay Time	Q1	—	6.9	—	ns	Q1 V _{DD} = 15V, V _{GS} = 4.5V I _D = 6.1A Q2 V _{DD} = 15V, V _{GS} = 4.5V I _D = 8.8A Clamped Inductive Load
		Q2	—	7.8	—		
t _r	Rise Time	Q1	—	7.3	—		
		Q2	—	10	—		
t _{d(off)}	Turn-Off Delay Time	Q1	—	10	—		
		Q2	—	15	—		
t _f	Fall Time	Q1	—	3.2	—	pF	V _{GS} = 0V V _{DS} = 15V f = 1.0MHz
		Q2	—	4.6	—		
C _{iss}	Input Capacitance	Q1	—	910	—		
		Q2	—	1780	—		
C _{oss}	Output Capacitance	Q1	—	190	—		
		Q2	—	390	—		
C _{rss}	Reverse Transfer Capacitance	Q1	—	94	—	pF	
		Q2	—	180	—		

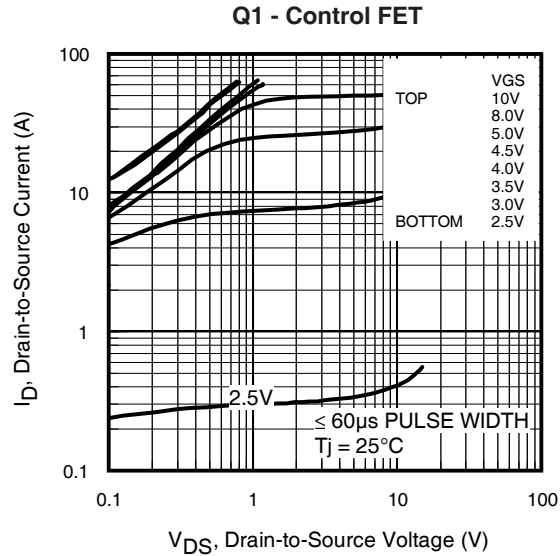
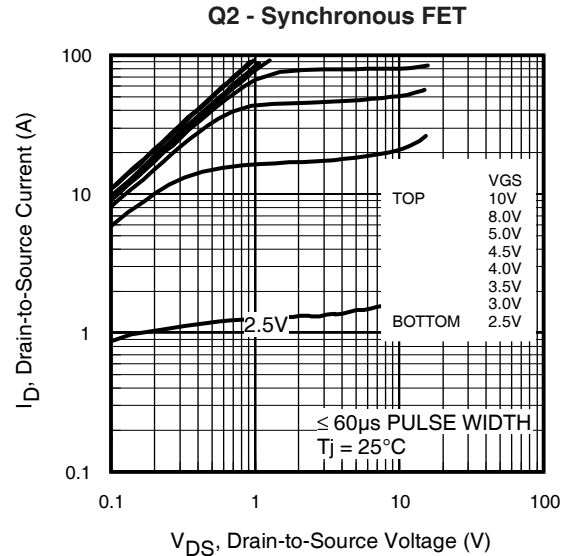
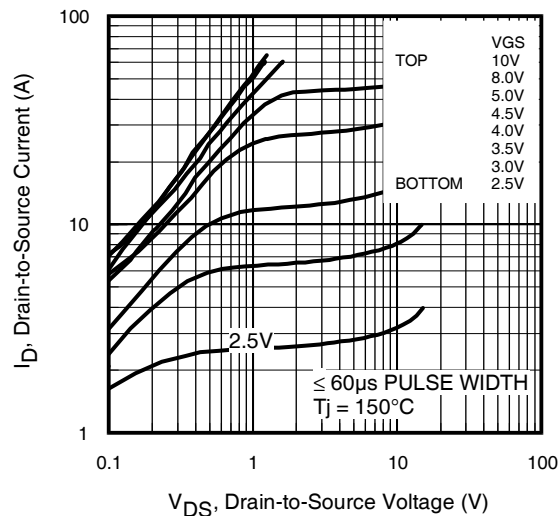
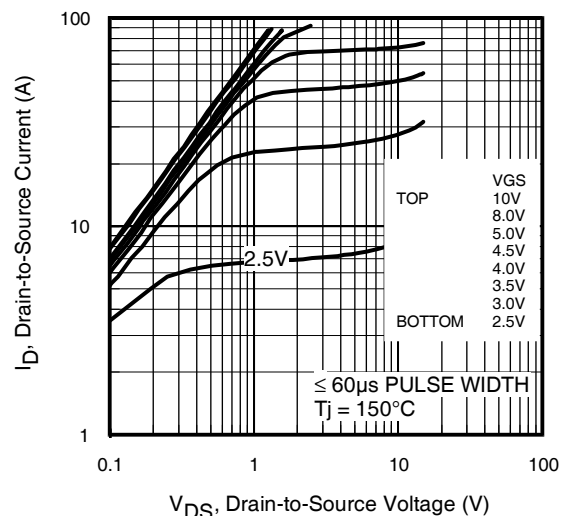
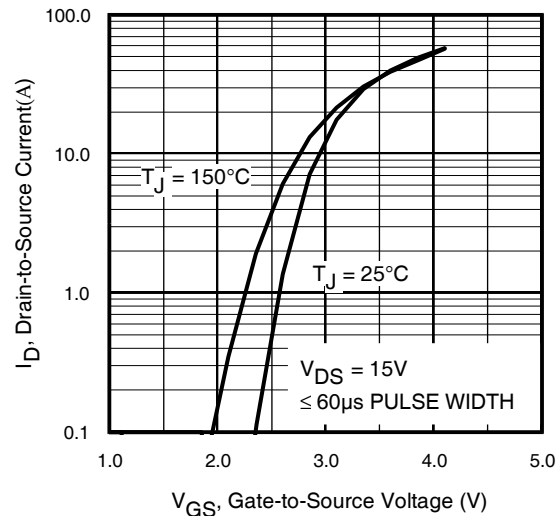
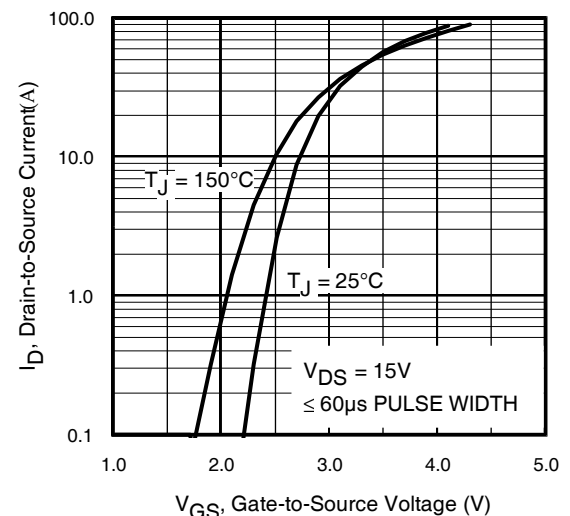
Avalanche Characteristics

	Parameter	Typ.	Q1 Max.	Q2 Max.	Units
E _{AS}	Single Pulse Avalanche Energy ②	—	140	250	mJ
I _{AR}	Avalanche Current ①	—	6.1	8.8	A

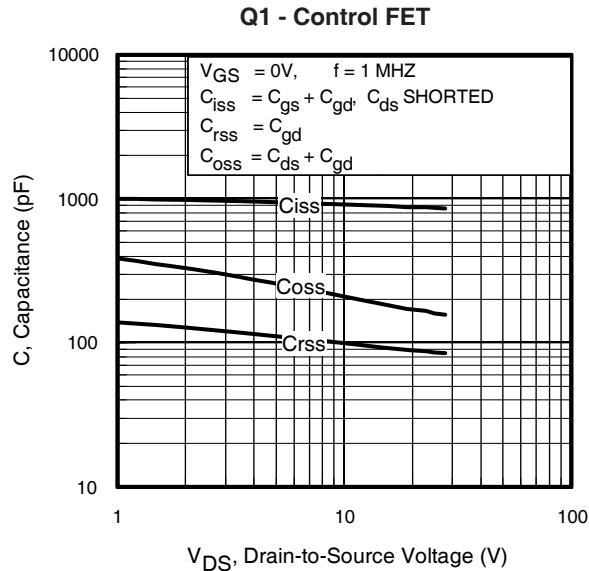
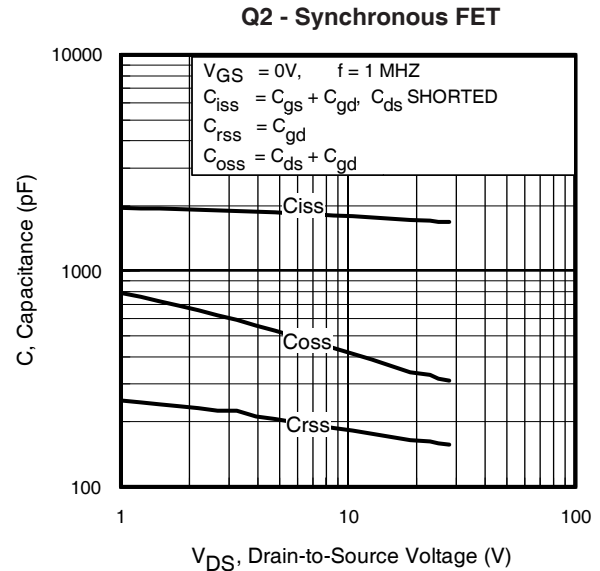
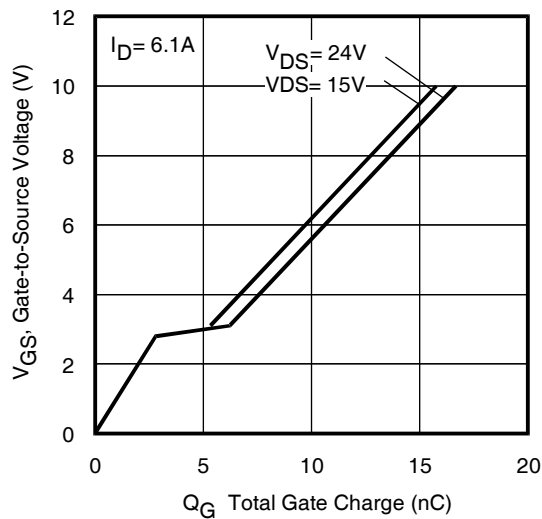
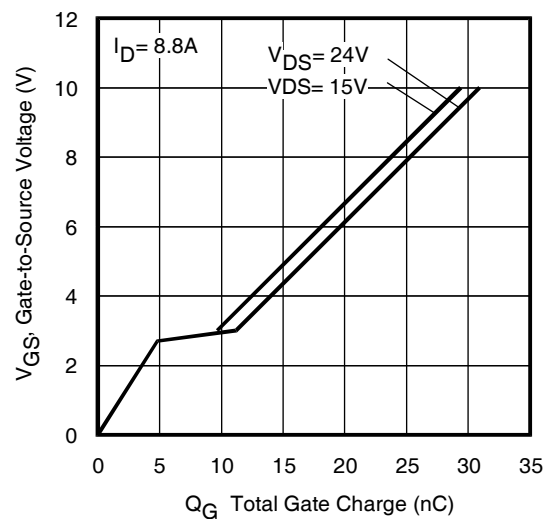
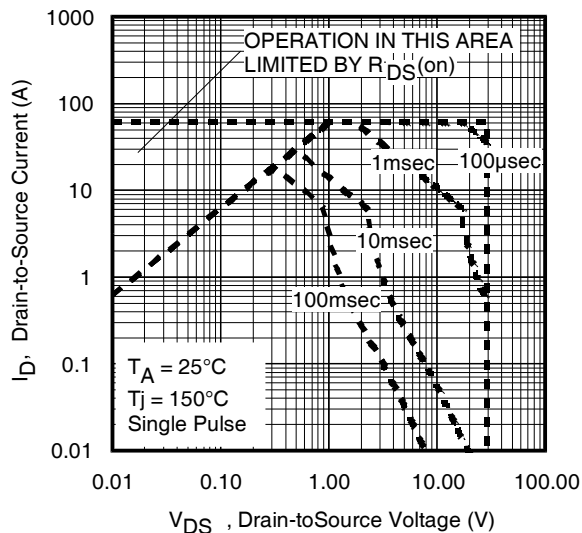
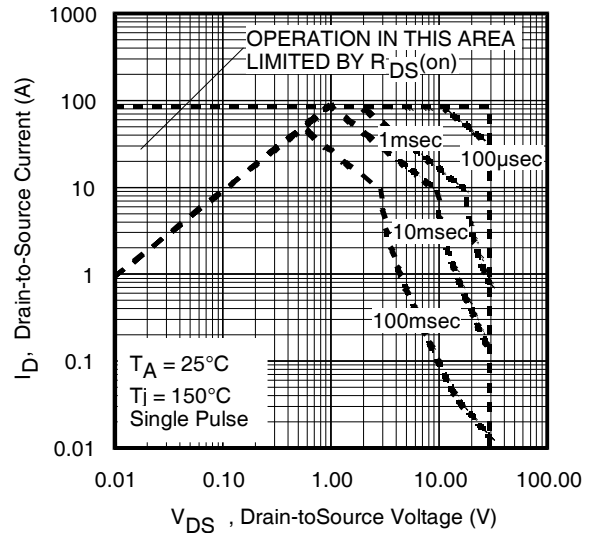
Diode Characteristics

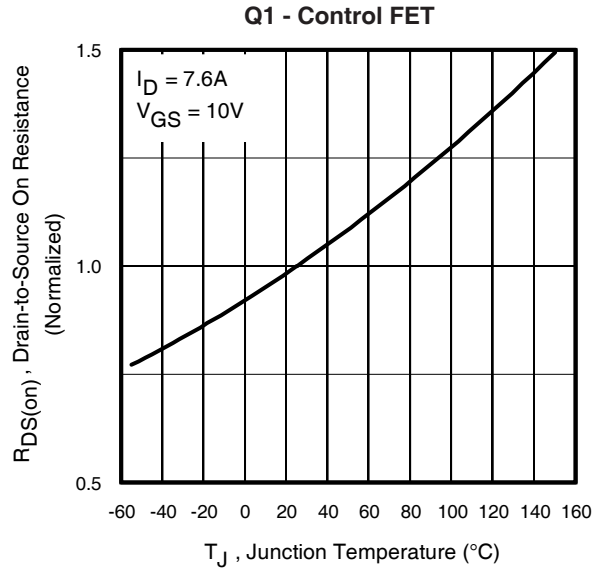
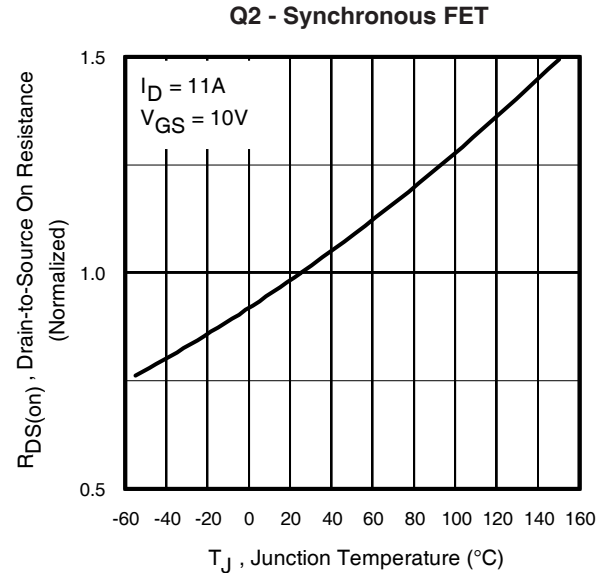
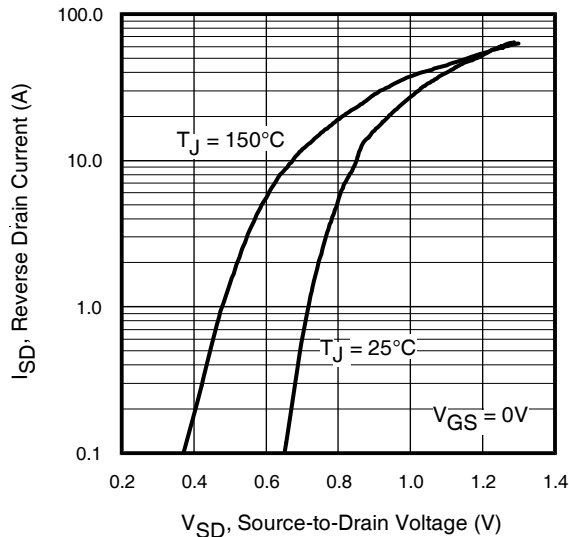
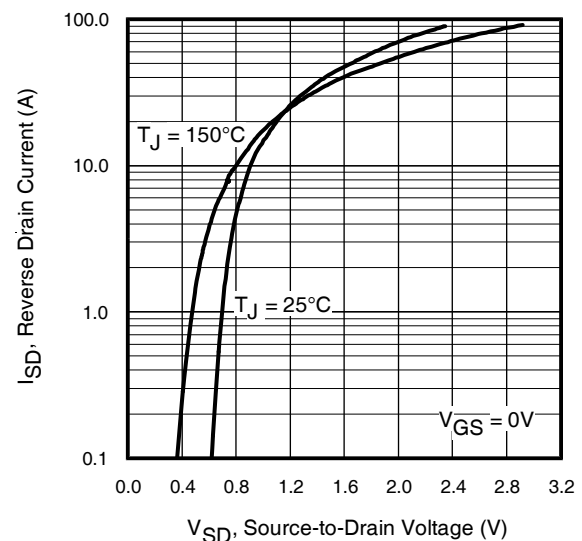
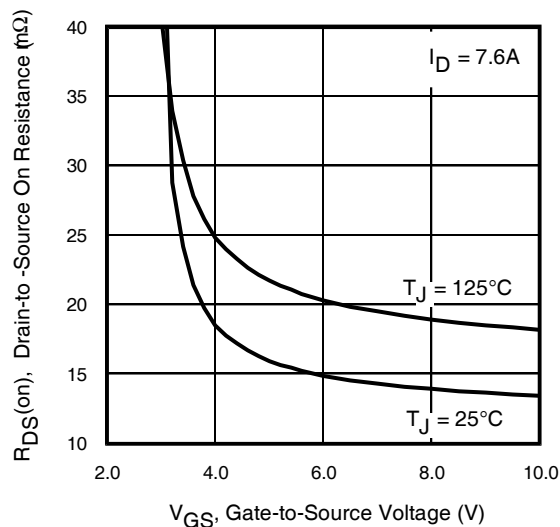
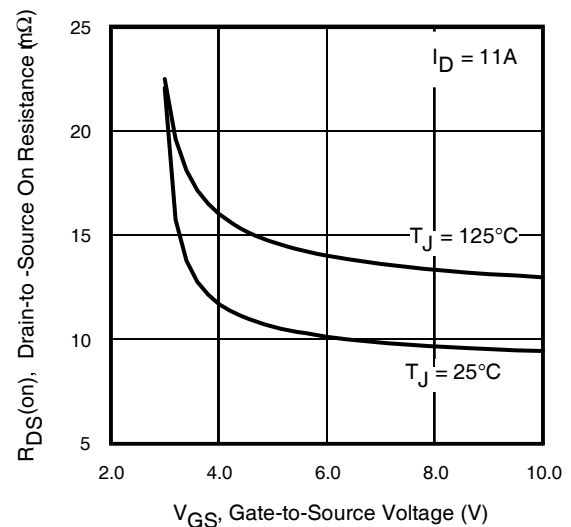
	Parameter		Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	Q1	—	—	1.8	A	MOSFET symbol showing the integral reverse p-n junction diode. 
		Q2	—	—	2.5		
I _{SM}	Pulsed Source Current (Body Diode) ①	Q1	—	—	61	A	T _J = 25°C, I _S = 6.1A, V _{GS} = 0V ③
		Q2	—	—	88		
V _{SD}	Diode Forward Voltage	Q1	—	—	1.0	V	T _J = 25°C, I _S = 8.8A, V _{GS} = 0V ③
		Q2	—	—	1.0		
t _{rr}	Reverse Recovery Time	Q1	—	11	17	ns	Q1 T _J = 25°C, I _F = 6.1A, V _{DD} = 15V, di/dt = 100A/μs ③
		Q2	—	16	24		
Q _{rr}	Reverse Recovery Charge	Q1	—	2.6	3.9	nC	Q2 T _J = 25°C, I _F = 8.8A, V _{DD} = 15V, di/dt = 100A/μs ③
		Q2	—	6.9	10		

Typical Characteristics


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics

Fig 3. Typical Output Characteristics

Fig 4. Typical Output Characteristics

Fig 5. Typical Transfer Characteristics

Fig 6. Typical Transfer Characteristics

Typical Characteristics


Fig 7. Typical Capacitance vs. Drain-to-Source Voltage

Fig 8. Typical Capacitance vs. Drain-to-Source Voltage

Fig 9. Typical Gate Charge vs. Gate-to-Source Voltage

Fig 10. Typical Gate Charge vs. Gate-to-Source Voltage

Fig 11. Maximum Safe Operating Area

Fig 12. Maximum Safe Operating Area

Typical Characteristics

Fig 13. Normalized On-Resistance vs. Temperature

Fig 14. Normalized On-Resistance vs. Temperature

Fig 15. Typical Source-Drain Diode Forward Voltage

Fig 16. Typical Source-Drain Diode Forward Voltage

Fig 17. Typical On-Resistance vs. Gate Voltage

Fig 18. Typical On-Resistance vs. Gate Voltage

Typical Characteristics

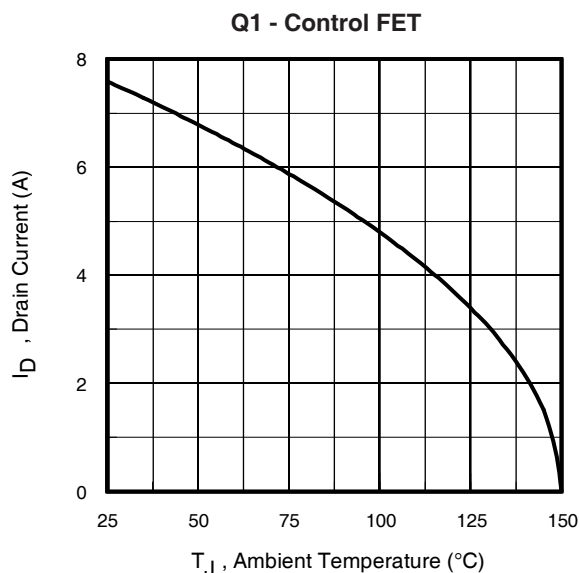


Fig 19. Maximum Drain Current vs. Ambient Temp.

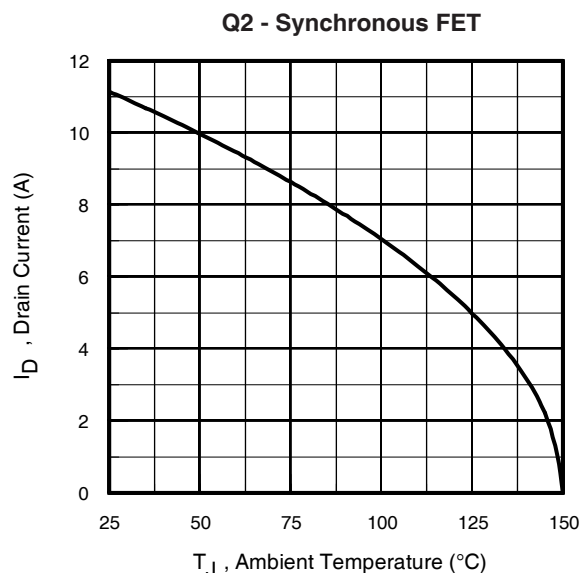


Fig 20. Maximum Drain Current vs. Ambient Temp.

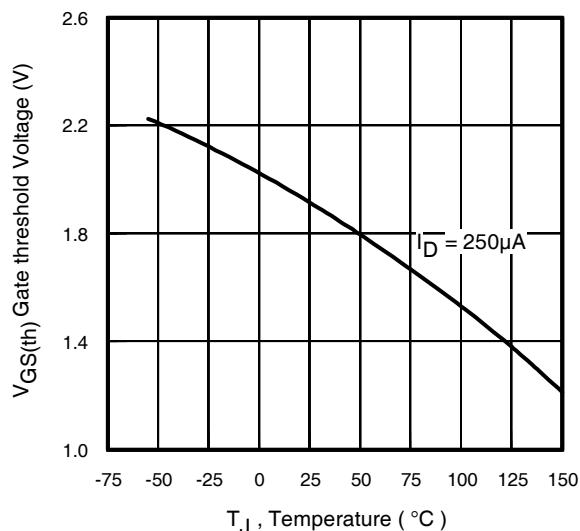


Fig 21. Threshold Voltage vs. Temperature

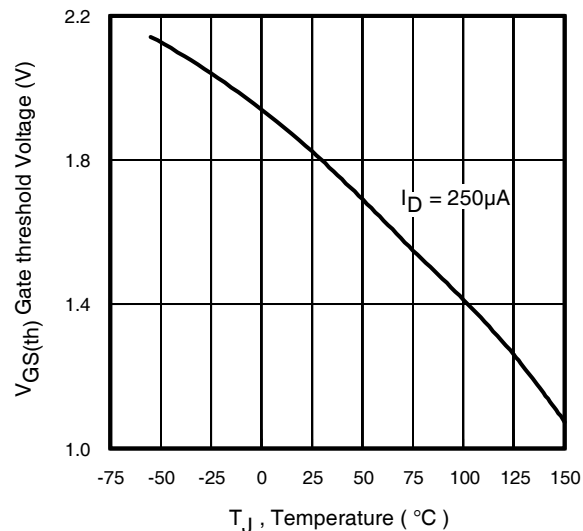


Fig 22. Threshold Voltage vs. Temperature

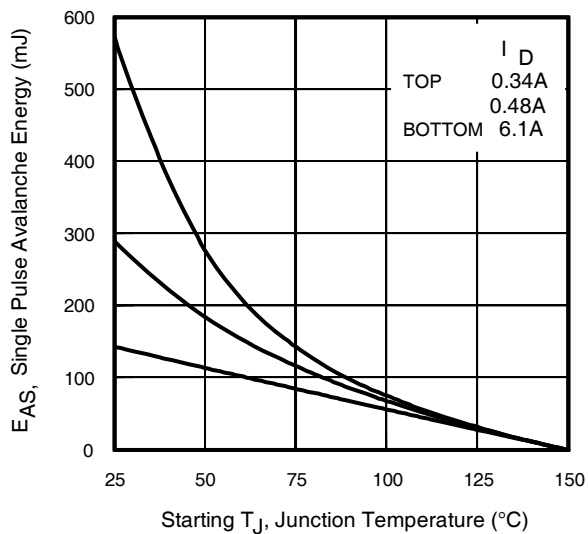


Fig 23. Maximum Avalanche Energy vs. Drain Current

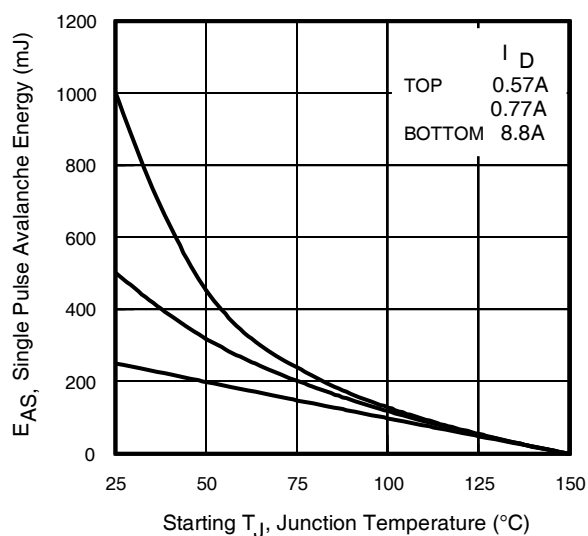
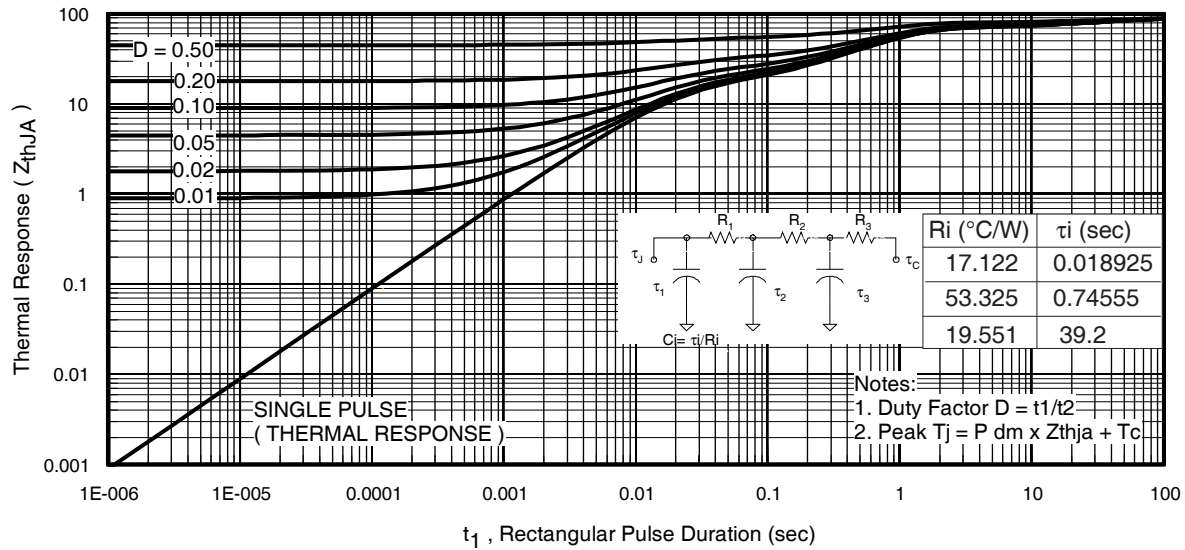
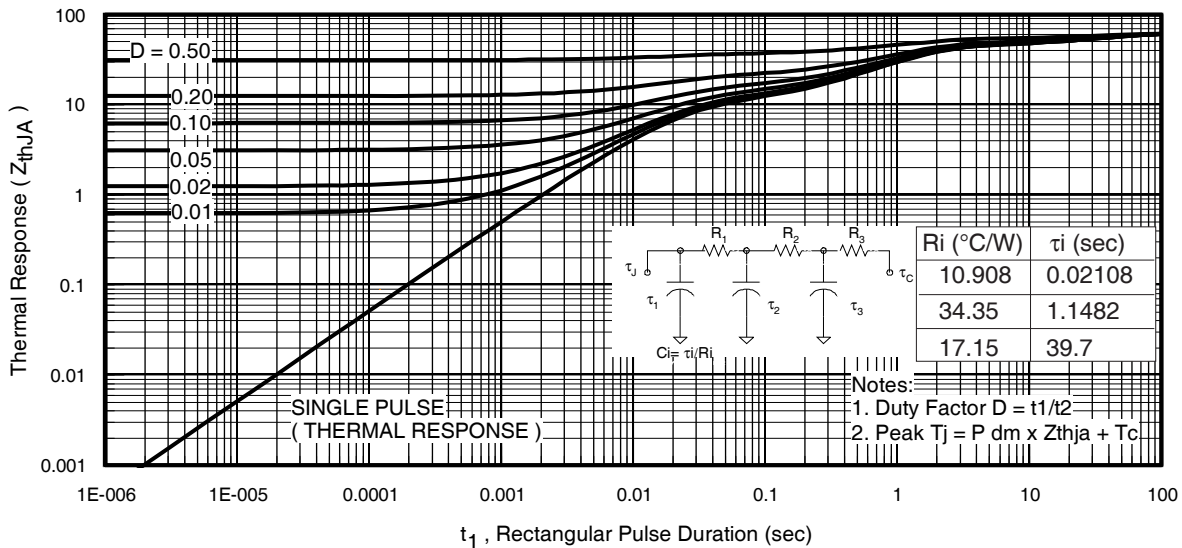
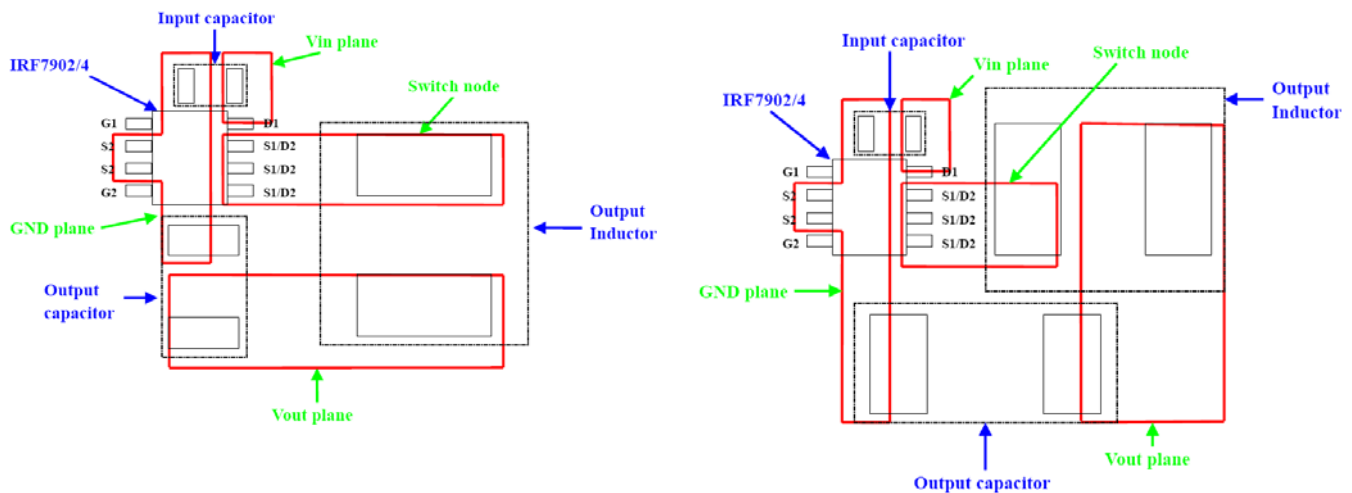
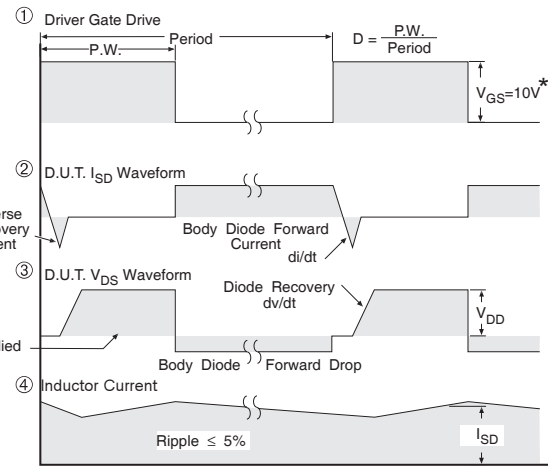
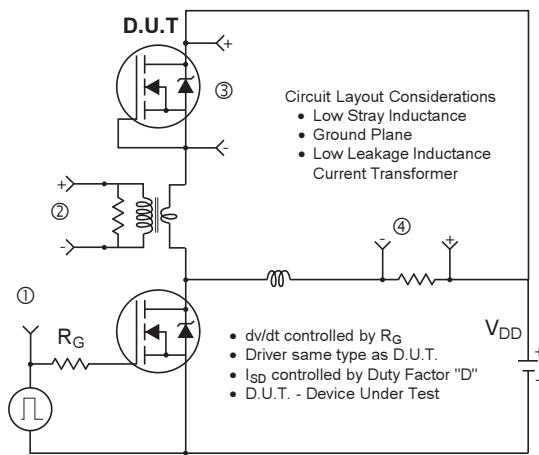


Fig 24. Maximum Avalanche Energy vs. Drain Current


Fig 25. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient (Q1)

Fig 26. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient (Q2)

Fig 27. Layout Diagram



* $V_{GS} = 5V$ for Logic Level Devices

Fig 28. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET® Power MOSFETs

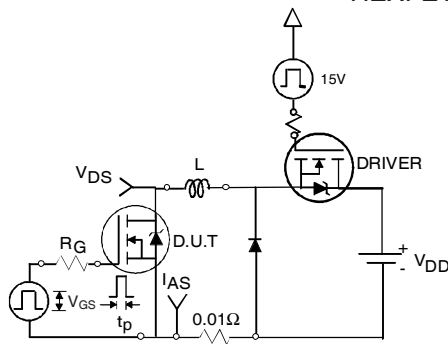


Fig 29a. Unclamped Inductive Test Circuit

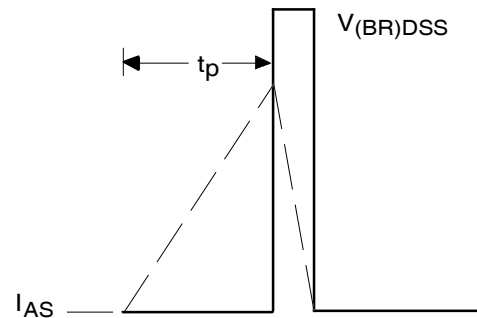


Fig 29b. Unclamped Inductive Waveforms

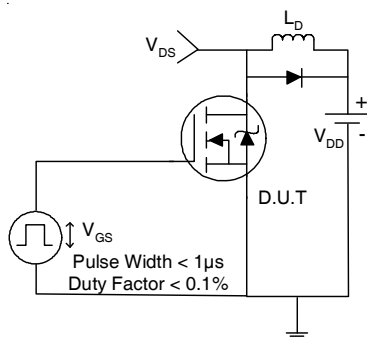


Fig 30a. Switching Time Test Circuit

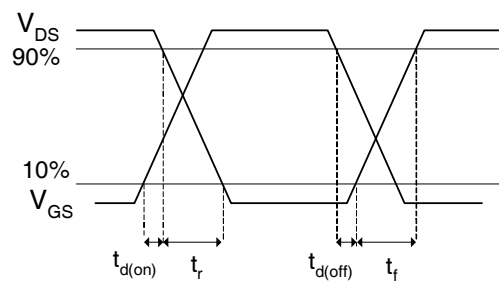


Fig 30b. Switching Time Waveforms

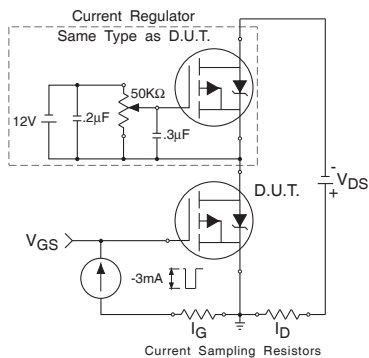


Fig 31a. Gate Charge Test Circuit

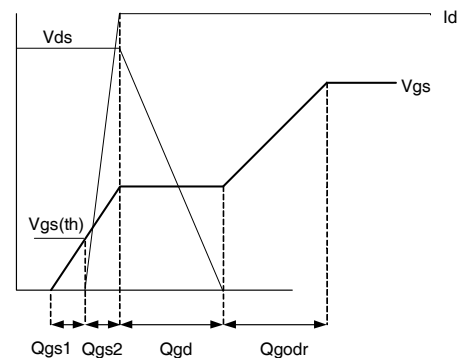
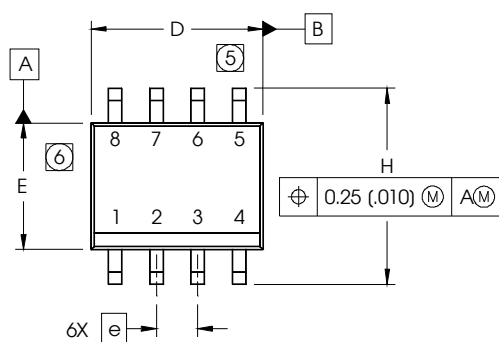


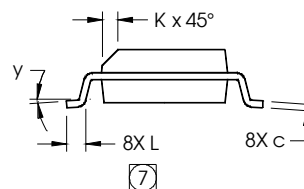
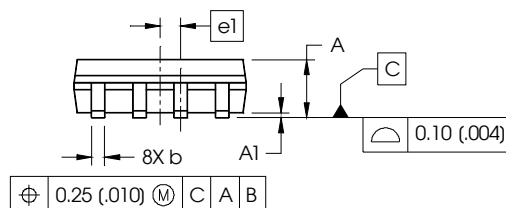
Fig 31b. Gate Charge Waveform

SO-8 Package Outline

Dimensions are shown in millimeters (inches)



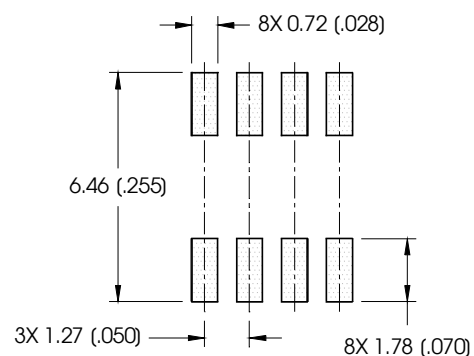
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
Y	0°	8°	0°	8°



NOTES:

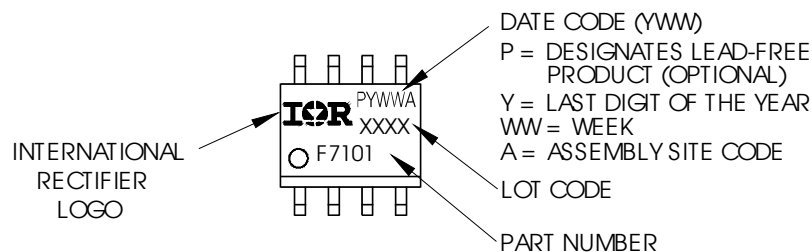
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 (.006).
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 (.010).
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

FOOTPRINT

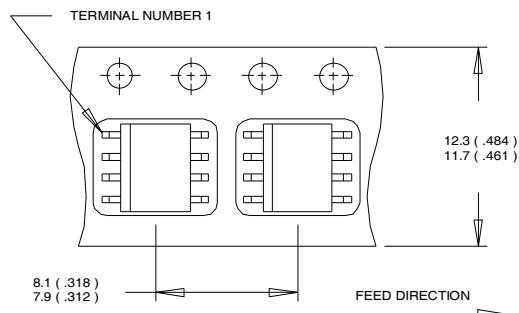


SO-8 Part Marking

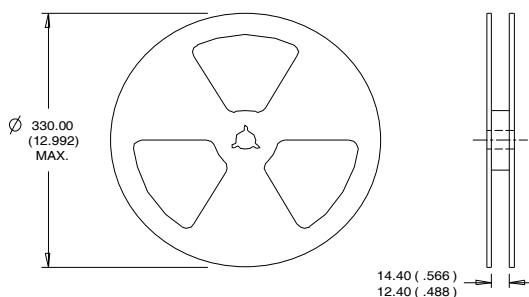
EXAMPLE: THIS IS AN IRF7101 (MOSFET)



Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

SO-8 Tape and Reel (Dimensions are shown in millimeters (inches))


- NOTES:
1. CONTROLLING DIMENSION : MILLIMETER.
 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



- NOTES :
1. CONTROLLING DIMENSION : MILLIMETER.
 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Note: For the most current drawing please refer to IR website at <http://www.irf.com/package/>

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting $T_J = 25^\circ\text{C}$, Q1: $L = 7.7\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 6.1\text{A}$; Q2: $L = 6.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 8.8\text{A}$.
- ③ Pulse width $\leq 400\mu\text{s}$; duty cycle $\leq 2\%$.
- ④ When mounted on 1 inch square copper board.
- ⑤ R_θ is measured at T_J approximately 90°C .

Qualification information[†]

Qualification level	Industrial (per JEDEC JESD47F ^{††} guidelines)	
Moisture Sensitivity Level	SO-8	MSL1 (per JEDEC J-STD-020D ^{††})
RoHS compliant	Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/product-info/reliability>

^{††} Applicable version of JEDEC standard at the time of product release

International
 Rectifier

IR WORLD HEADQUARTERS: 101 N. Sepulveda Blvd., El Segundo, California 90245, USA
To contact International Rectifier, please visit <http://www.irf.com/whoto-call/>